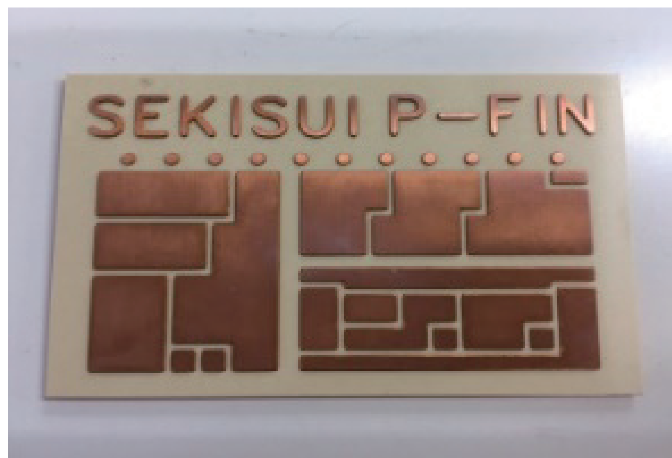
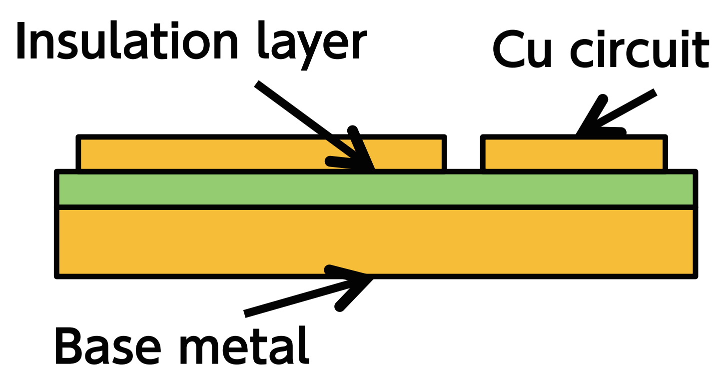
放熱樹脂基板

Resin Substrate (Epoxy)

樹脂基板「P-Fin」 Resin Substrate “P-Fin”

1.製品 Product

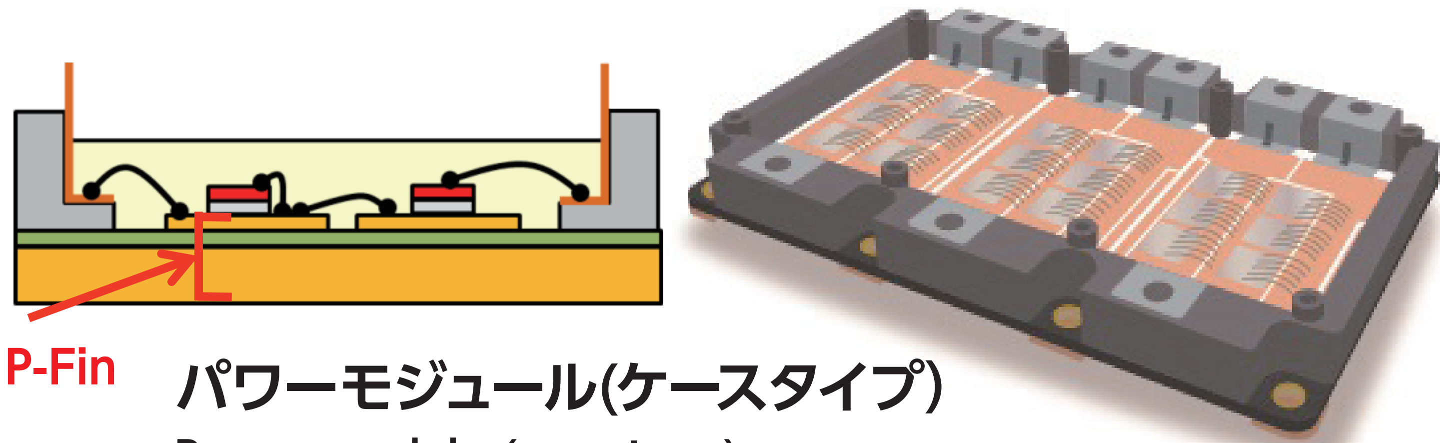




2.物性 Property

Item	10W type	12W type
Thickness	＞125 um	＞125 um
λ	10 W/m･K	12 W/m･K
Tg	190℃	190℃
BDV（AC)	＞4.0 kV	＞4.0 kV

3.用途 Application



パワーモジュール(ケースタイプ)
Power module (case type)

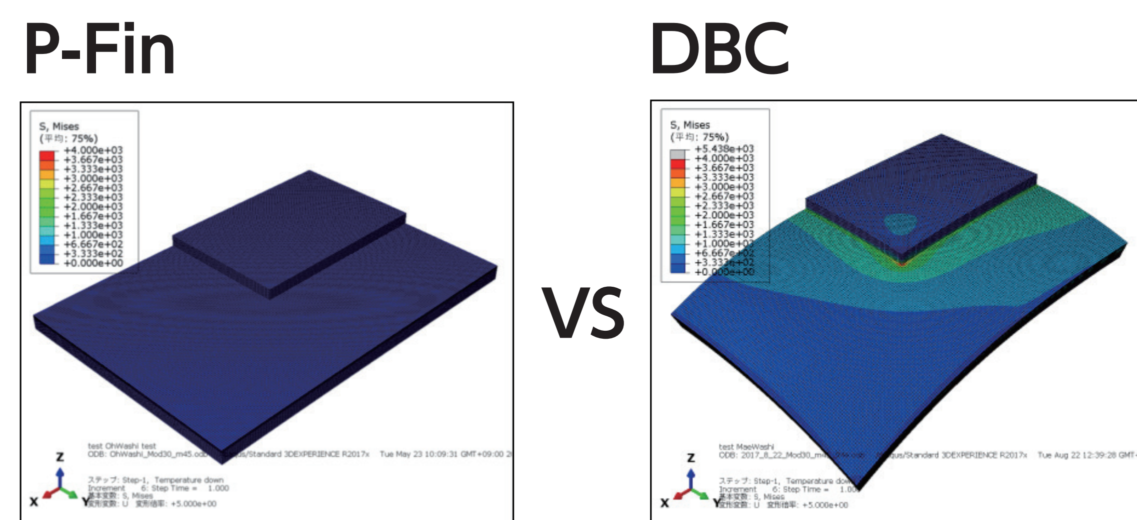
4.特性 Features

- 薄膜高絶縁かつ高熱伝導率
  Both high insulation with thin film and high thermal conductivity.
- 信頼性の高い絶縁層
  Reliable insulation layer
- 厚金属の適用可能
  Thick metal available

5.信頼性 Reliability

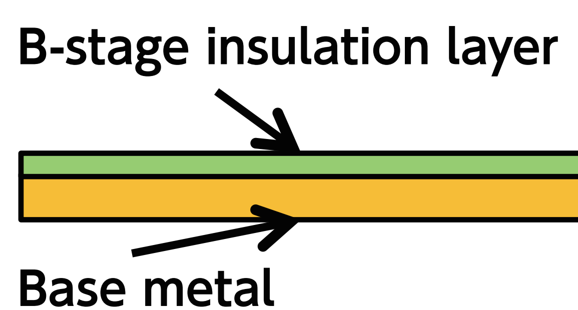
Item	Test condition			Break down
P-Fin 10W	150℃	2.0 kV	2,000 hrs	○ (N=10)
	85℃85%RH	2.0 kV	2,000 hrs	○ (N=10)

6.応力シミュレーション Stress Simulation



B-stage 樹脂基板「N-Fin」 B-stage Resin Substrate “N-Fin”

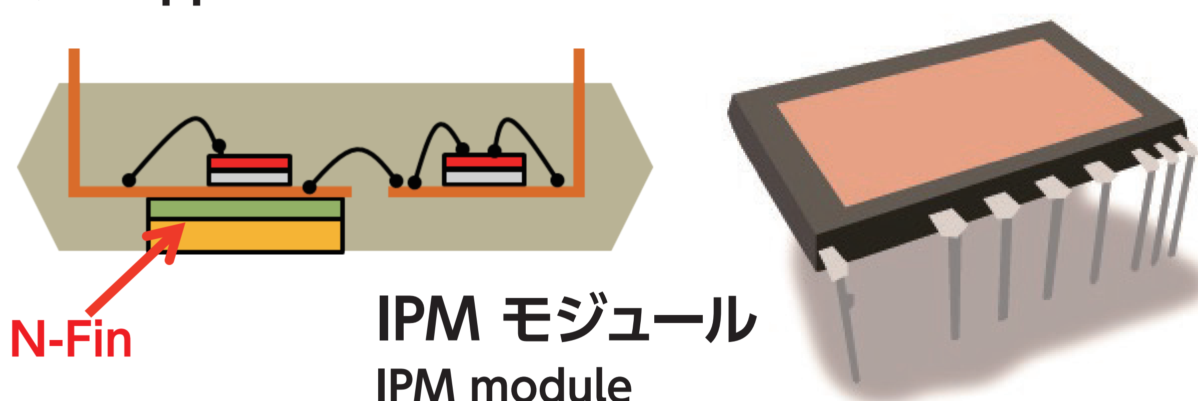
1.製品 Product



2.物性 Property

Item	3 W type	8 W type
Thickness	160 um	160 um
λ	3 W/m･K	8 W/m･K
Tg	120℃	190℃
BDV (AC)	＞4.0 kV	＞4.0 kV

3.用途 Application



IPM モジュール
IPM module

4.特性 Features

- 接着性のある絶縁層
  Adhesive B-stage insulation layer

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